BGA Package
144-Lead (16mm x 16mm x 7.07mm)
(Reference LTC DWG # 05-08-1937 Rev D)

NOTES:
1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M-1994
2. ALL DIMENSIONS ARE IN MILLIMETERS. DRAWING NOT TO SCALE
3. BALL DESIGNATION PER JEP95
4. DETAILS OF PIN #1 IDENTIFIER ARE OPTIONAL, BUT MUST BE LOCATED WITHIN THE ZONE INDICATED. THE PIN #1 IDENTIFIER MAY BE EITHER A MOLD OR MARKED FEATURE
5. PRIMARY DATUM -Z- IS SEATING PLANE
6. SOLDER BALL COMPOSITION CAN BE 96.5% Sn/3.0% Ag/0.5% Cu OR Sn Pb EUTECTIC

PACKAGE TOP VIEW

PACKAGE BOTTOM VIEW

SUGGESTED PCB LAYOUT

TOTAL NUMBER OF BALLS: 144